

# AN15076

## Multi-protocol implementation on the i.MX RT1180 MCU

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Application note

### Document information

| Information | Content                                                                                                                                                                                                                                                                                                                    |
|-------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Keywords    | AN15076, i.MX RT1180 MCU, EtherCAT, NETC, PHY, MII, RGMII                                                                                                                                                                                                                                                                  |
| Abstract    | This document describes a method for multi-protocol implementation on the i.MX RT1180 MCU that supports 100 Mbit/s (MII) and 1000 Mbit/s (RGMII) with shared hardware. The proposed method uses a single PHY with software-configurable modes, enabling both EtherCAT and NETC. It reduces complexity and lowers the cost. |



## 1 Introduction

The NXP i.MX RT1180 crossover MCU integrates both EtherCAT and NETC Ethernet communication capabilities.

- The EtherCAT interface operates at 100 Mbit/s and typically connects to Fast Ethernet PHYs via an MII interface.
- The NETC interface supports 1000 Mbit/s operation and is commonly connected to gigabit PHYs through an RGMII interface.

Pin multiplexing is implemented between the EtherCAT and NETC interfaces. Therefore, different application scenarios require corresponding configurations of external PHY connections, IOMUX settings, clock sources, and MAC interface modes.

The MIMXRT1180-EVK (also called i.MX RT1180-EVK) board uses two dedicated PHY configurations to support EtherCAT and NETC independently:

- A 100 Mbit/s PHY connected via MII for EtherCAT
- A 1000 Mbit/s PHY connected via RGMII for NETC.

While this architecture simplifies independent functional validation, it increases hardware cost, resource consumption, and overall system complexity when switching between the two modes.

This document describes a more efficient design by using a single Ethernet PHY that supports both MII and RGMII interfaces, as well as 100 Mbit/s and 1000 Mbit/s operation. Through software reconfiguration, the PHY can operate in MII/100 Mbit/s mode for EtherCAT or switch to RGMII/1000 Mbit/s mode for NETC. This unified approach allows both communication protocols to share a single PHY, significantly reducing hardware complexity while enhancing system flexibility. So, this paper presents a system-level solution for implementing both EtherCAT and NETC functionalities using a single Ethernet PHY.

## 2 EtherCAT application

In the EtherCAT application, the shared Ethernet PHY is configured to operate in MII mode with a link speed of 100 Mbit/s. In this mode, the PHY is connected to the i.MX RT1180 EtherCAT controller through the MII signal group, and the system is optimized for deterministic real-time industrial communication.

This section describes the hardware connection, clock and pin multiplexing requirements, software initialization flow, and basic validation result for running EtherCAT over the shared PHY solution.

### 2.1 Hardware configuration

For EtherCAT operation, the external PHY is configured as a 100 Mbit/s Fast Ethernet PHY using the MII interface. The MII transmit and receive data signals, management interface signals, reference clock, and reset signal are connected between the i.MX RT1180 EtherCAT MAC and the shared PHY.

The IOMUX configuration must select the EtherCAT MII function for the corresponding pins. Since the pins are multiplexed between EtherCAT and NETC functions, the NETC RGMII pin function must be disabled when the system operates in EtherCAT mode.

The PHY can work with both MII and RGMII. However, the clock configuration for these two modes is completely different. Therefore, the hardware must meet the MII timing requirement. Typically, a 25 MHz reference clock is used for 100 Mbit/s MII operation. Figures [Figure 1](#), [Figure 2](#), and [Figure 3](#) describe the hardware clock configuration.

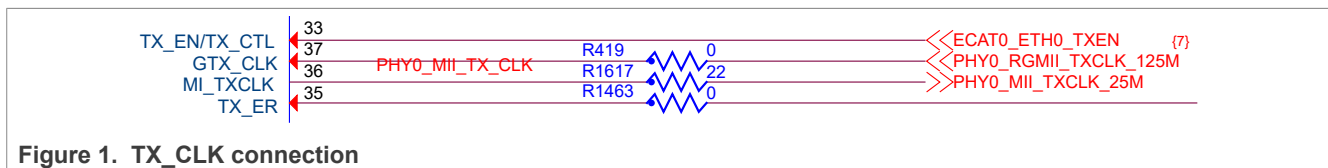


Figure 1. TX\_CLK connection

As shown in [Figure 1](#), the MII\_TX\_CLK works as the output from PHY side and RGMII\_TX\_CLK\_125M works as the input from PHY side. The PHY separates these two signals to two pins.

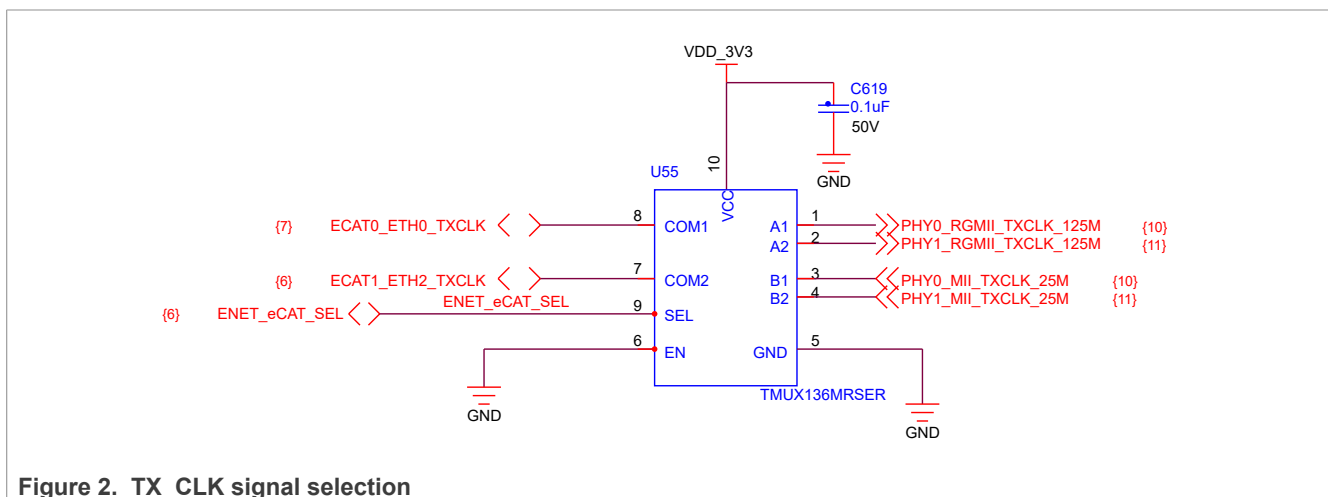


Figure 2. TX\_CLK signal selection

From the MCU side, the NETC RGMII TXCLK uses the same pin as the EtherCAT MII TXCLK. Therefore, an analog switch must be used to choose the right TX\_CLK signal. As shown in [Figure 2](#), the ENET\_eCAT\_SEL signal connects to a GPIO of i.MX RT1180 MCU. The software code enables selection of the right signal for different modes.

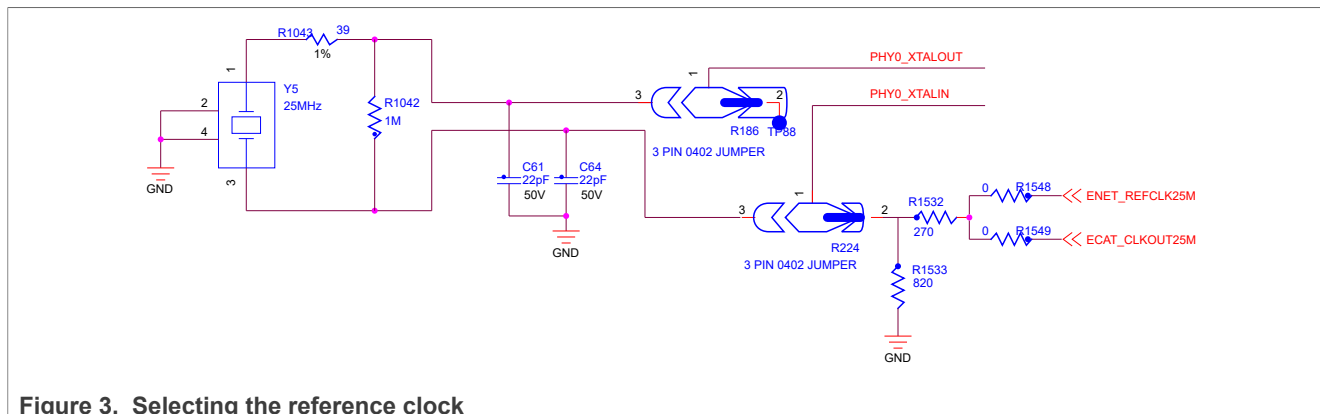


Figure 3. Selecting the reference clock

Additionally, EtherCAT has a stricter requirement for the reference clock. It is recommended to let the EtherCAT controller provide the reference clock to the PHY, so that the hardware can choose the right reference clock. As described in [Figure 3](#), three methods for providing reference clock to the PHY are reserved in the design. Resistors are used to distinguish whether a crystal oscillator or an MCU provides the reference clock. The MCU software configuration is used to select the clock provider from the MCU.

For details of the PHY configuration used on a sample board, refer to the [Section 7](#).

## 2.2 Software configuration

During EtherCAT initialization, the software first configures the IOMUX pins for the EtherCAT MII interface, I2C interface, and MDIO interface and enables the required clock sources. The PHY reset sequence is then executed to ensure that the PHY starts from a known state.

After reset, the software accesses the PHY through ECAT MDIO to configure the register to set it as MII mode. This step is done because the default pin strapping configuration for this PHY is RGMII mode. The second configuration for the PHY is to configure the LED function. As the ECAT\_LINK signal is connected to the LED pin of the PHY, you must configure the LED0 to indicate the link status of the PHY.

For deterministic EtherCAT operation, the final link mode must be confirmed as 100 Mbit/s full-duplex mode.

For the PHY configuration, refer to the code below:

```
/* Set the auto negotiation advertisement mode to 100M*/
ECAT_EscMdioWrite(ECAT, 0x01, 0x04, 0x1e1);
/* Disable the 1000Base-T capability to avoid negotiating to 1000M */
ECAT_EscMdioWrite(ECAT, 0x01, 0x09, 0x00);
/* Restart auto negotiation */
ECAT_EscMdioWrite(ECAT, 0x01, 0x00, 0x1240);
/* Set the LED0 feature as link status indication */
ECAT_EscMdioWrite(ECAT, 0x01, 0x1E, 0x401);
```

Then, initialize the EtherCAT controller with MII as the MAC interface mode. After the PHY link connection is established, the EtherCAT stack can start the SubDevice initialization process and enter the normal EtherCAT state transition flow, including INIT, PRE-OP, SAFE-OP, and OP states.

## 2.3 Test results

The EtherCAT application was verified by configuring the shared PHY in MII 100 Mbit/s mode and connecting the board to an EtherCAT MainDevice. After initialization, the PHY link was successfully established at 100 Mbit/s, and the EtherCAT detected the SubDevice.

The SubDevice completed the standard EtherCAT state transition and entered OP state successfully. Process data communication was verified between the EtherCAT MainDevice and the i.MX RT1180 EtherCAT SubDevice. Results confirm that the shared PHY solution can support EtherCAT communication in MII 100 Mbit/s mode.

[Table 1](#) shows a typical EtherCAT solution validation result.

Table 1. EtherCAT application validation result

| Test item                    | Expected result                  | Test result |
|------------------------------|----------------------------------|-------------|
| PHY interface mode           | MI                               | Pass        |
| Link speed and mode          | 100 Mbit/s full-duplex           | Pass        |
| EtherCAT SubDevice detection | SubDevice detected by MainDevice | Pass        |
| EtherCAT state transition    | INIT to OP                       | Pass        |
| Process data exchange        | Cyclic data communication normal | Pass        |

### 3 NETC application

In the NETC application, the Ethernet PHY is configured to operate in RGMII mode with a link speed of 1000 Mbit/s. In this mode, the PHY is connected to the RT1180 NETC Ethernet controller and provides high-bandwidth Ethernet communication for general network applications and other industrial networking protocols such as ProfNet, TSN, and others.

This section describes the hardware connection, pin multiplexing, clock configuration, software initialization flow, and basic validation result for running Gigabit Ethernet over the shared PHY solution.

#### 3.1 Hardware configuration

For NETC operation, the external PHY is configured as a Gigabit Ethernet PHY using the RGMII interface. The RGMII transmit and receive data signals, control signals, clock signals, MDIO/MDC management interface, reset signal, and interrupt signal are connected between the RT1180 NETC MAC and the shared PHY.

The IOMUX configuration must select the NETC function for the corresponding pins. Since the pins are multiplexed between EtherCAT and NETC functions, the EtherCAT pin function must be disabled when the system operates in NETC mode.

The clock configuration for RGMII is different, because the TX\_CLK signal in RGMII mode is output from the MAC side. As shown in the [Figure 2](#), the ENET\_eCAT\_SEL must be pulled low to let the MAC TX\_CLK connect to the GTX\_CLK of the PHY.

The RGMII interface also has a timing delay adjustment requirement. Configure the PHY and MAC consistently for RGMII internal delay or external PCB delay. The PHY must be configured to advertise and establish a 1000 Mbit/s full-duplex link.

Because every PHY has a default pin strapping configuration, which can make the PHY work in a specific mode after reset. [Figure 4](#) shows the default pin strapping for the MIMXRT1180-EVK design.

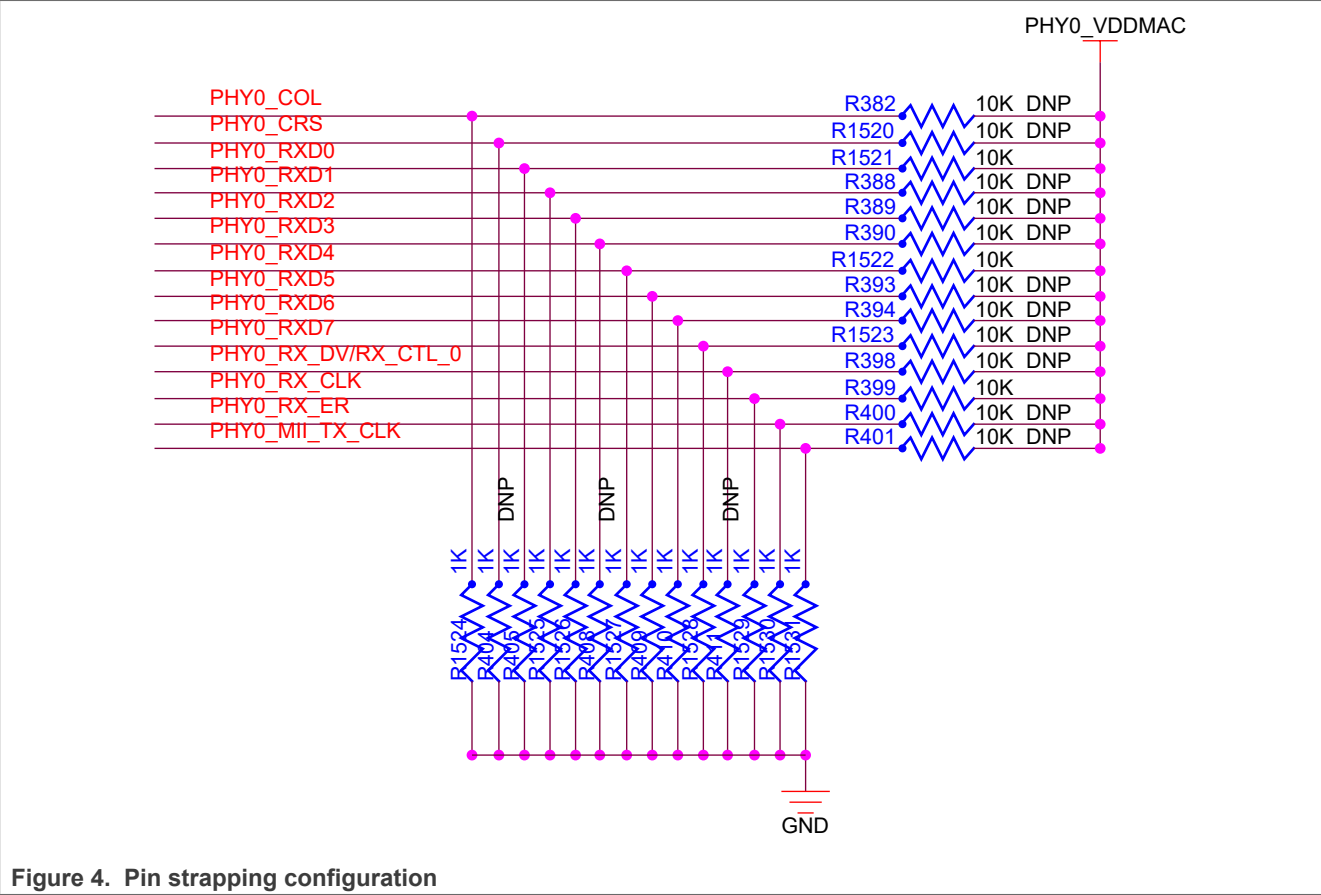


Figure 4. Pin strapping configuration

This setting configures the PHY work as RGMII 1000M full-duplex mode and adds 2 ns delay to both TX\_CLK and RX\_CLK.

### 3.2 Software configuration

During NETC initialization, the software first configures the IOMUX pins for the NETC RGMII interface and enables the required NETC and Ethernet clock sources. The clock for NETC MACs should be set to output 125 MHz to follow the requirement of RGMII. The PHY reset sequence is then performed before PHY register configuration.

After reset, the software initializes the MDIO interface and configures the PHY to auto-negotiation mode due to the pin strapping already set the PHY work as 1000M RGMII FDX. After auto-negotiation is complete, the software checks the link status and confirms that the link is established at 1000 Mbit/s.

The NETC driver is then initialized with RGMII as the MAC interface mode. Network parameters, such as MAC address, IP address, gateway, and subnet mask, are configured according to the target application. After the network interface is up, standard Ethernet communication can be verified by ping, TCP/UDP traffic, or throughput testing.

### 3.3 Test results

The NETC application was verified by configuring the shared PHY in RGMII 1000 Mbit/s mode and connecting the board to a Gigabit Ethernet link partner. After initialization and auto-negotiation, the PHY link was successfully established at 1000 Mbit/s full-duplex operation.

Basic network communication was verified by the NETC transfer test. The result confirms that the shared PHY solution supports NETC Gigabit Ethernet communication in RGMII 1000 Mbit/s mode.

[Table 2](#) shows a typical NETC application validation result.

Table 2. NETC solution validation result

| Test item           | Expected result         | Test result |
|---------------------|-------------------------|-------------|
| PHY interface mode  | RGMII                   | Pass        |
| Link speed and mode | 1000 Mbit/s Full-Duplex | Pass        |
| Tx Rx transfer test | Successful response     | Pass        |

## 4 Conclusion

### 4.1 Overall comparison of the solutions

[Table 3](#) provides a comparison of the two solutions, conventional and the proposed.

**Table 3. Feature comparison of the solutions**

| Parameter           | Dual PHY solution  | Single PHY solution (Proposed) |
|---------------------|--------------------|--------------------------------|
| Number of PHYs      | 2                  | 1                              |
| Supported protocols | EtherCAT + NETC    | EtherCAT + NETC                |
| Hardware complexity | High               | Reduced                        |
| BOM cost            | High               | Lower                          |
| PCB routing         | Complex            | Simplified                     |
| Mode switching      | Hardware selection | Software-controlled            |
| System flexibility  | Limited            | High                           |

As seen in the preceding table, the proposed single PHY architecture enables efficient hardware resource reuse and significantly reduces system cost while improving flexibility.

### 4.2 EtherCAT versus NETC configuration comparison

[Table 4](#) shows the feature comparison of EtherCAT and NETC.

**Table 4. Comparison of EtherCAT versus NETC configuration parameters**

| Parameter / Feature | EtherCAT mode                | NETC mode                 |
|---------------------|------------------------------|---------------------------|
| Interface           | MII                          | RGMII                     |
| Link speed          | 100 Mbit/s                   | 1000 Mbit/s               |
| Duplex              | Full-duplex                  | Full-duplex               |
| MAC controller      | EtherCAT controller          | NETC controller           |
| Pin multiplexing    | EtherCAT pins enabled        | NETC pins enabled         |
| TX_CLK direction    | PHY → MAC                    | MAC → PHY                 |
| Reference clock     | 25 MHz                       | 125 MHz                   |
| PHY configuration   | Forced 100M                  | Auto-negotiation          |
| Typical use case    | Real-time industrial control | High-bandwidth networking |

### 4.3 Hardware design differences

[Table 5](#) lists the hardware design differences EtherCAT and NETC.

**Table 5. EtherCAT and NETC hardware design differences**

| Parameter       | EtherCAT mode | NETC mode  |
|-----------------|---------------|------------|
| PHY interface   | MII           | RGMII      |
| TX_CLK source   | PHY output    | MAC output |
| Clock frequency | 25 MHz        | 125 MHz    |

Table 5. EtherCAT and NETC hardware design differences...continued

| Parameter              | EtherCAT mode                          | NETC mode                  |
|------------------------|----------------------------------------|----------------------------|
| Clock selection        | Switch required                        | Switch required            |
| Pinmux switching       | Required                               | Required                   |
| RGMII delay            | Not applicable                         | Required (internal or PCB) |
| Reference clock source | Preferable to use the MCU clock source | MCU or Crystal             |

## 4.4 Software initialization flow comparison

[Table 6](#) shows the comparison of software initialization flow for EtherCAT and NETC.

Table 6. Software initialization flow comparison for EtherCAT and NETC

| Step                 | EtherCAT mode           | NETC mode            |
|----------------------|-------------------------|----------------------|
| IOMUX configuration  | Configure MII pins      | Configure RGMII pins |
| Clock initialization | 25 MHz                  | 125 MHz              |
| PHY reset            | Required                | Required             |
| PHY configuration    | Force 100 Mbit/s        | Auto-negotiation     |
| MAC initialization   | EtherCAT controller     | NETC MAC             |
| Upper-layer stack    | EtherCAT protocol stack | TCP/IP, TSN stack    |

## 4.5 Mode switching impact

[Table 7](#) provides a comparison of the mode switching impact of EtherCAT and NETC.

Table 7. Mode switching impact of EtherCAT and NETC

| Aspect               | Impact                                            |
|----------------------|---------------------------------------------------|
| Pinmux switching     | Must be consistent to avoid communication failure |
| Clock path selection | Must match the selected mode                      |
| TX_CLK direction     | Critical difference between modes                 |
| PHY configuration    | Must override default strap settings if needed    |
| Software sequence    | Reset → PHY config → MAC initialization           |

## 5 Acronyms

[Table 8](#) describes the acronyms and abbreviations listed in this document.

**Table 8. Acronyms and abbreviations**

| Acronym  | Description                                 |
|----------|---------------------------------------------|
| BOM      | Bill of Materials                           |
| ECAT     | EtherCAT                                    |
| EtherCAT | Ethernet for Control Automation Technology  |
| EVK      | Evaluation Kit                              |
| FAE      | Field Applications Engineer                 |
| FDX      | Full Duplex                                 |
| GPIO     | General-Purpose Input/Output                |
| IOMUX    | Input/Output Multiplexer                    |
| IP       | Internet Protocol                           |
| MAC      | Media Access Control                        |
| MCU      | Microcontroller Unit                        |
| MDC      | Management Data Clock                       |
| MDIO     | Management Data Input/Output                |
| MII      | Media Independent Interface                 |
| NDA      | Non-Disclosure Agreement                    |
| NETC     | Network Enabler and Traffic Controller      |
| PCB      | Printed Circuit Board                       |
| PHY      | Physical Layer Device                       |
| PSIRT    | Product Security Incident Response Team     |
| RGMII    | Reduced Gigabit Media Independent Interface |
| TCP      | Transmission Control Protocol               |
| TSN      | Time-Sensitive Networking                   |
| UDP      | User Datagram Protocol                      |

## 6 Related documentation

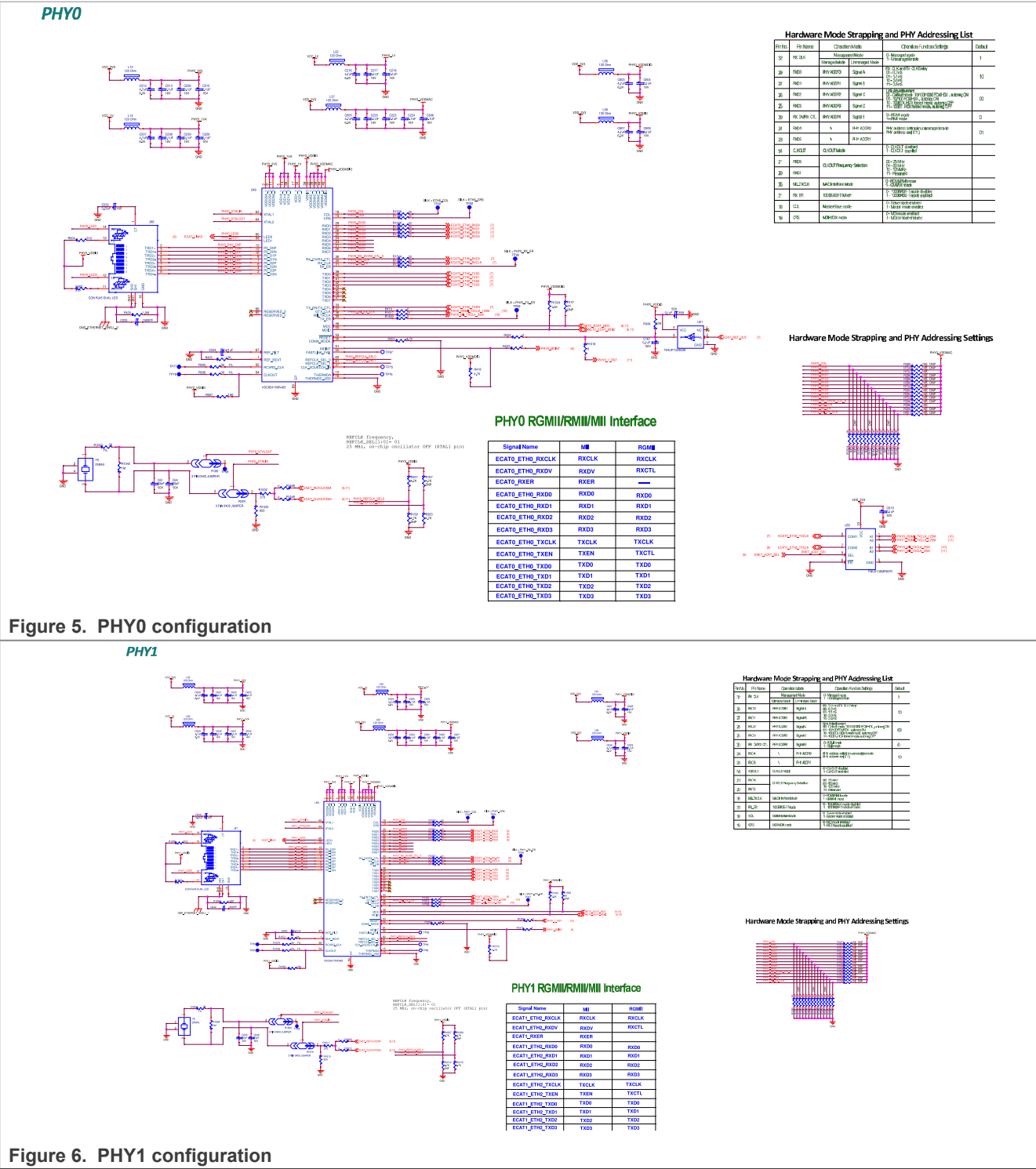
[Table 9](#) lists and explains the additional documents and resources that can be referred to for more information. For the i.MX RT1180 product details, refer to the [i.MX RT1180 web page](#). More documentation is available at the URL: [i.MX RT1180 documentation](#).

Table 9. Related documentation

| Document title                              | Description                                                                                                                    | Link/how to access          |
|---------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|-----------------------------|
| i.MX RT1180 reference manual                | Provides a detailed description about the i.MX RT1180 MCU and its features, including memory maps, power supplies, and clocks. | <a href="#">IMXRT1180RM</a> |
| i.MX RT1180 crossover processors data sheet | Provides information about electrical characteristics, hardware design considerations, and ordering information                | <a href="#">IMXRT1180EC</a> |

7 Appendix

Figure 5 and Figure 6 describe the configurations that can be used to implement the design described in this document.



## 8 Revision history

[Table 10](#) summarizes revisions to this document.

Table 10. Revision history

| Document ID   | Release date | Description            |
|---------------|--------------|------------------------|
| AN15076 v.1.0 | 15 July 2026 | Initial public release |

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Contents

1 Introduction ..... 2

2 EtherCAT application ..... 3

2.1 Hardware configuration ..... 3

2.2 Software configuration ..... 4

2.3 Test results ..... 4

3 NETC application ..... 6

3.1 Hardware configuration ..... 6

3.2 Software configuration ..... 7

3.3 Test results ..... 7

4 Conclusion ..... 9

4.1 Overall comparison of the solutions ..... 9

4.2 EtherCAT versus NETC configuration comparison ..... 9

4.3 Hardware design differences ..... 9

4.4 Software initialization flow comparison ..... 10

4.5 Mode switching impact ..... 10

5 Acronyms ..... 11

6 Related documentation ..... 12

7 Appendix ..... 13

8 Revision history ..... 14

Legal information ..... 15

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